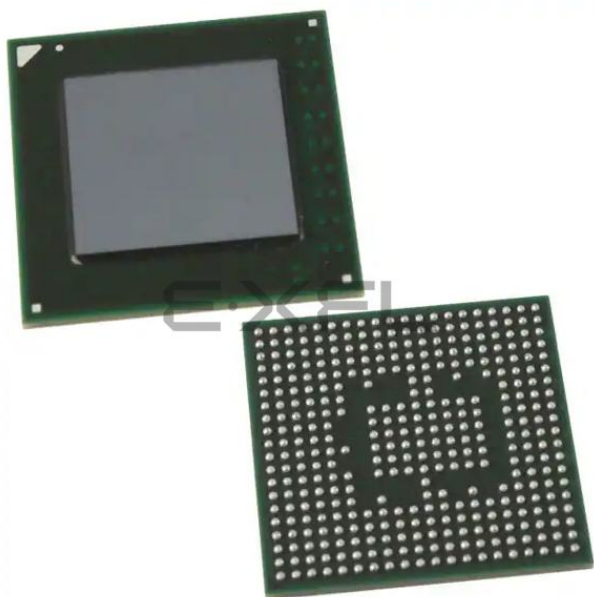




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	1805
Number of Logic Elements/Cells	42959
Total RAM Bits	3517440
Number of I/O	156
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	358-LFBGA, FCBGA
Supplier Device Package	358-UBGA, FCBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep2agx45cu17c6n

Table 1–5. Recommended Operating Conditions for Arria II GX Devices (Note 1) (Part 2 of 2)

Symbol	Description	Condition	Minimum	Typical	Maximum	Unit
t_{RAMP}	Power Supply Ramp time	Normal POR	0.05	—	100	ms
		Fast POR	0.05	—	4	ms

Notes to Table 1–5:

- (1) For more information about supply pin connections, refer to the *Arria II Device Family Pin Connection Guidelines*.
- (2) Altera recommends a 3.0-V nominal battery voltage when connecting V_{CCBAT} to a battery for volatile key backup. If you do not use the volatile security key, you may connect the V_{CCBAT} to either GND or a 3.0-V power supply.
- (3) V_{CCPD} must be 2.5-V for I/O banks with 2.5-V and lower V_{CCIO} , 3.0-V for 3.0-V V_{CCIO} , and 3.3-V for 3.3-V V_{CCIO} .
- (4) V_{CCIO} for 3C and 8C I/O banks where the configuration pins reside only supports 3.3-, 3.0-, 2.5-, or 1.8-V voltage levels.

Table 1–6 lists the recommended operating conditions for Arria II GZ devices.

Table 1–6. Recommended Operating Conditions for Arria II GZ Devices (Note 6) (Part 1 of 2)

Symbol	Description	Condition	Minimum	Typical	Maximum	Unit
V_{CC}	Core voltage and periphery circuitry power supply	—	0.87	0.90	0.93	V
V_{CCCB}	Supplies power for the configuration RAM bits	—	1.45	1.50	1.55	V
V_{CCAUX}	Auxiliary supply	—	2.375	2.5	2.625	V
V_{CCPD} (2)	I/O pre-driver (3.0 V) power supply	—	2.85	3.0	3.15	V
	I/O pre-driver (2.5 V) power supply	—	2.375	2.5	2.625	V
V_{CCIO}	I/O buffers (3.0 V) power supply	—	2.85	3.0	3.15	V
	I/O buffers (2.5 V) power supply	—	2.375	2.5	2.625	V
	I/O buffers (1.8 V) power supply	—	1.71	1.8	1.89	V
	I/O buffers (1.5 V) power supply	—	1.425	1.5	1.575	V
	I/O buffers (1.2 V) power supply	—	1.14	1.2	1.26	V
V_{CCPGM}	Configuration pins (3.0 V) power supply	—	2.85	3.0	3.15	V
	Configuration pins (2.5 V) power supply	—	2.375	2.5	2.625	V
	Configuration pins (1.8 V) power supply	—	1.71	1.8	1.89	V
$V_{\text{CCA_PLL}}$	PLL analog voltage regulator power supply	—	2.375	2.5	2.625	V
$V_{\text{CCD_PLL}}$	PLL digital voltage regulator power supply	—	0.87	0.90	0.93	V
$V_{\text{CC_CLKIN}}$	Differential clock input power supply	—	2.375	2.5	2.625	V
V_{CCBAT} (1)	Battery back-up power supply (For design security volatile key register)	—	1.2	—	3.3	V
V_{I}	DC input voltage	—	–0.5	—	3.6	V
V_{O}	Output voltage	—	0	—	V_{CCIO}	V
$V_{\text{CCA_L}}$	Transceiver high voltage power (left side)	—	2.85/2.375	3.0/2.5 (4)	3.15/2.625	V
$V_{\text{CCA_R}}$	Transceiver high voltage power (right side)					
$V_{\text{CCHIP_L}}$	Transceiver HIP digital power (left side)	—	0.87	0.9	0.93	V
$V_{\text{CCR_L}}$	Receiver power (left side)	—	1.05	1.1	1.15	V
$V_{\text{CCR_R}}$	Receiver power (right side)	—	1.05	1.1	1.15	V
$V_{\text{CCT_L}}$	Transmitter power (left side)	—	1.05	1.1	1.15	V
$V_{\text{CCT_R}}$	Transmitter power (right side)	—	1.05	1.1	1.15	V

Table 1-6. Recommended Operating Conditions for Arria II GZ Devices (Note 6) (Part 2 of 2)

Symbol	Description	Condition	Minimum	Typical	Maximum	Unit
V_{CCL_GXBLn} (3)	Transceiver clock power (left side)	—	1.05	1.1	1.15	V
V_{CCL_GXBRn} (3)	Transceiver clock power (right side)	—	1.05	1.1	1.15	V
V_{CCH_GXBLn} (3)	Transmitter output buffer power (left side)	—	1.33/1.425	1.4/1.5 (5)	1.575	V
V_{CCH_GXBRn} (3)	Transmitter output buffer power (right side)	—				
T_J	Operating junction temperature	Commercial	0	—	85	°C
		Industrial	–40	—	100	°C
t_{RAMP}	Power supply ramp time	Normal POR (PORSEL=0)	0.05	—	100	ms
		Fast POR (PORSEL=1)	0.05	—	4	ms

Notes to Table 1-6:

- (1) Altera recommends a 3.0-V nominal battery voltage when connecting V_{CCBAT} to a battery for volatile key backup. If you do not use the volatile security key, you may connect the V_{CCBAT} to either GND or a 3.0-V power supply.
- (2) V_{CCPD} must be 2.5 V when V_{CCIO} is 2.5, 1.8, 1.5, or 1.2 V. V_{CCPD} must be 3.0 V when V_{CCIO} is 3.0 V.
- (3) $n = 0, 1, \text{ or } 2$.
- (4) $V_{CCA_L/R}$ must be connected to a 3.0-V supply if the clock multiplier unit (CMU) phase-locked loop (PLL), receiver clock data recovery (CDR), or both, are configured at a base data rate > 4.25 Gbps. For data rates up to 4.25 Gbps, you can connect $V_{CCA_L/R}$ to either 3.0 V or 2.5 V.
- (5) $V_{CCH_GXBL/R}$ must be connected to a 1.4-V supply if the transmitter channel data rate is > 6.5 Gbps. For data rates up to 6.5 Gbps, you can connect $V_{CCH_GXBL/R}$ to either 1.4 V or 1.5 V.
- (6) Transceiver power supplies do not have power-on-reset (POR) circuitry. After initial power-up, violating the transceiver power supply operating conditions could lead to unpredictable link behavior.

DC Characteristics

This section lists the supply current, I/O pin leakage current, on-chip termination (OCT) accuracy and variation, input pin capacitance, internal weak pull-up and pull-down resistance, hot socketing, and Schmitt trigger input specifications.

Supply Current

Standby current is the current the device draws after the device is configured with no inputs or outputs toggling and no activity in the device. Because these currents vary largely with the resources used, use the Microsoft Excel-based Early Power Estimator (EPE) to get supply current estimates for your design.



For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter.

The calibration accuracy for calibrated series and parallel OCTs are applicable at the moment of calibration. When process, voltage, and temperature (PVT) conditions change after calibration, the tolerance may change.

Table 1-13 lists the Arria II GZ OCT without calibration resistance tolerance to PVT changes.

Table 1-13. OCT Without Calibration Resistance Tolerance Specifications for Arria II GZ Devices

Symbol	Description	Conditions (V)	Resistance Tolerance		Unit
			C3,I3	C4,I4	
25-Ω R _S 3.0 and 2.5	25-Ω internal series OCT without calibration	V _{CCIO} = 3.0, 2.5	± 40	± 40	%
25-Ω R _S 1.8 and 1.5	25-Ω internal series OCT without calibration	V _{CCIO} = 1.8, 1.5	± 40	± 40	%
25-Ω R _S 1.2	25-Ω internal series OCT without calibration	V _{CCIO} = 1.2	± 50	± 50	%
50-Ω R _S 3.0 and 2.5	50-Ω internal series OCT without calibration	V _{CCIO} = 3.0, 2.5	± 40	± 40	%
50-Ω R _S 1.8 and 1.5	50-Ω internal series OCT without calibration	V _{CCIO} = 1.8, 1.5	± 40	± 40	%
50-Ω R _S 1.2	50-Ω internal series OCT without calibration	V _{CCIO} = 1.2	± 50	± 50	%
100-Ω R _D 2.5	100-Ω internal differential OCT	V _{CCIO} = 2.5	± 25	± 25	%

OCT calibration is automatically performed at power up for OCT-enabled I/Os. When voltage and temperature conditions change after calibration, the resistance may change. Use Equation 1-1 and Table 1-14 to determine the OCT variation when voltage and temperature vary after power-up calibration for Arria II GX and GZ devices.

Equation 1-1. OCT Variation (Note 1)

$$R_{OCT} = R_{SCAL} \left(1 + \left\langle \frac{dR}{dT} \times \Delta T \right\rangle \pm \left\langle \frac{dR}{dV} \times \Delta V \right\rangle \right)$$

Notes to Equation 1-1:

- (1) R_{OCT} value calculated from Equation 1-1 shows the range of OCT resistance with the variation of temperature and V_{CCIO}.

Table 1-19 lists the weak pull-up resistor values for Arria II GZ devices.

Table 1-19. Internal Weak Pull-Up Resistor for Arria II GZ Devices (Note 1), (2)

Symbol	Description	Conditions	Min	Typ	Max	Unit
R _{PU}	Value of the I/O pin pull-up resistor before and during configuration, as well as user mode if the programmable pull-up resistor option is enabled.	V _{CCIO} = 3.0 V ±5% (3)	—	25	—	kΩ
		V _{CCIO} = 2.5 V ±5% (3)	—	25	—	kΩ
		V _{CCIO} = 1.8 V ±5% (3)	—	25	—	kΩ
		V _{CCIO} = 1.5 V ±5% (3)	—	25	—	kΩ
		V _{CCIO} = 1.2 V ±5% (3)	—	25	—	kΩ

Notes to Table 1-19:

- (1) All I/O pins have an option to enable weak pull-up except configuration, test, and JTAG pins.
- (2) The internal weak pull-down feature is only available for the JTAG TCK pin. The typical value for this internal weak pull-down resistor is approximately 25 kΩ.
- (3) Pin pull-up resistance values may be lower if an external source drives the pin higher than V_{CCIO}.

Hot Socketing

Table 1-20 lists the hot-socketing specification for Arria II GX and GZ devices.

Table 1-20. Hot Socketing Specifications for Arria II Devices

Symbol	Description	Maximum
I _{IOPIN(DC)}	DC current per I/O pin	300 μA
I _{IOPIN(AC)}	AC current per I/O pin	8 mA (1)
I _{XCVRTX(DC)}	DC current per transceiver TX pin	100 mA
I _{XCVRRX(DC)}	DC current per transceiver RX pin	50 mA

Note to Table 1-20:

- (1) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns, |I_{IOPIN}| = C dv/dt, in which “C” is I/O pin capacitance and “dv/dt” is slew rate.

Schmitt Trigger Input

The Arria II GX device supports Schmitt trigger input on the TDI, TMS, TCK, nSTATUS, nCONFIG, nCE, CONF_DONE, and DCLK pins. A Schmitt trigger feature introduces hysteresis to the input signal for improved noise immunity, especially for signals with slow edge rates.

Table 1-21 lists the hysteresis specifications across the supported V_{CCIO} range for Schmitt trigger inputs in Arria II GX devices.

Table 1-21. Schmitt Trigger Input Hysteresis Specifications for Arria II GX Devices

Symbol	Description	Condition (V)	Minimum	Unit
V _{Schmitt}	Hysteresis for Schmitt trigger input	V _{CCIO} = 3.3	220	mV
		V _{CCIO} = 2.5	180	mV
		V _{CCIO} = 1.8	110	mV
		V _{CCIO} = 1.5	70	mV

Table 1–23. Single-Ended I/O Standards for Arria II GZ Devices (Part 2 of 2)

I/O Standard	V_{CCIO} (V)			V_{IL} (V)		V_{IH} (V)		V_{OL} (V)	V_{OH} (V)	I_{OL} (mA)	I_{OH} (mA)
	Min	Typ	Max	Min	Max	Min	Max	Max	Min		
1.2 V	1.14	1.2	1.26	-0.3	$0.35 \times V_{CCIO}$	$0.65 \times V_{CCIO}$	$V_{CCIO} + 0.3$	$0.25 \times V_{CCIO}$	$0.75 \times V_{CCIO}$	2	-2
3.0-V PCI	2.85	3	3.15	—	$0.3 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	3.6	$0.1 \times V_{CCIO}$	$0.9 \times V_{CCIO}$	1.5	-0.5
3.0-V PCI-X	2.85	3	3.15	—	$0.35 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	—	$0.1 \times V_{CCIO}$	$0.9 \times V_{CCIO}$	1.5	-0.5

Table 1–24 lists the single-ended SSTL and HSTL I/O reference voltage specifications for Arria II GX devices.

Table 1–24. Single-Ended SSTL and HSTL I/O Reference Voltage Specifications for Arria II GX Devices

I/O Standard	V_{CCIO} (V)			V_{REF} (V)			V_{TT} (V)		
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max
SSTL-2 Class I, II	2.375	2.5	2.625	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	$V_{REF} - 0.04$	V_{REF}	$V_{REF} + 0.04$
SSTL-18 Class I, II	1.71	1.8	1.89	0.833	0.9	0.969	$V_{REF} - 0.04$	V_{REF}	$V_{REF} + 0.04$
SSTL-15 Class I, II	1.425	1.5	1.575	$0.47 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.53 \times V_{CCIO}$	$0.47 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.53 \times V_{CCIO}$
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	0.85	0.9	0.95
HSTL-15 Class I, II	1.425	1.5	1.575	0.71	0.75	0.79	0.71	0.75	0.79
HSTL-12 Class I, II	1.14	1.2	1.26	$0.48 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.52 \times V_{CCIO}$	—	$V_{CCIO}/2$	—

Table 1–25 lists the single-ended SSTL and HSTL I/O reference voltage specifications for Arria II GZ devices.

Table 1–25. Single-Ended SSTL and HSTL I/O Reference Voltage Specifications for Arria II GZ Devices

I/O Standard	V_{CCIO} (V)			V_{REF} (V)			V_{TT} (V)		
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max
SSTL-2 Class I, II	2.375	2.5	2.625	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	$V_{REF} - 0.04$	V_{REF}	$V_{REF} + 0.04$
SSTL-18 Class I, II	1.71	1.8	1.89	0.833	0.9	0.969	$V_{REF} - 0.04$	V_{REF}	$V_{REF} + 0.04$
SSTL-15 Class I, II	1.425	1.5	1.575	$0.47 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.53 \times V_{CCIO}$	$0.47 \times V_{CCIO}$	V_{REF}	$0.53 \times V_{CCIO}$
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	—	$V_{CCIO}/2$	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.68	0.75	0.9	—	$V_{CCIO}/2$	—
HSTL-12 Class I, II	1.14	1.2	1.26	$0.47 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.53 \times V_{CCIO}$	—	$V_{CCIO}/2$	—

Table 1-26 lists the single-ended SSTL and HSTL I/O standard signal specifications for Arria II GX devices.

Table 1-26. Single-Ended SSTL and HSTL I/O Standard Signal Specifications for Arria II GX Devices

I/O Standard	$V_{IL(DC)} (V)$		$V_{IH(DC)} (V)$		$V_{IL(AC)} (V)$	$V_{IH(AC)} (V)$	$V_{OL} (V)$	$V_{OH} (V)$	$I_{OL} (mA)$	$I_{OH} (mA)$
	Min	Max	Min	Max	Max	Min	Max	Min		
SSTL-2 Class I	-0.3	$V_{REF} - 0.18$	$V_{REF} + 0.18$	$V_{CCIO} + 0.3$	$V_{REF} - 0.35$	$V_{REF} + 0.35$	$V_{TT} - 0.57$	$V_{TT} + 0.57$	8.1	-8.1
SSTL-2 Class II	-0.3	$V_{REF} - 0.18$	$V_{REF} + 0.18$	$V_{CCIO} + 0.3$	$V_{REF} - 0.35$	$V_{REF} + 0.35$	$V_{TT} - 0.76$	$V_{TT} + 0.76$	16.4	-16.4
SSTL-18 Class I	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	$V_{CCIO} + 0.3$	$V_{REF} - 0.25$	$V_{REF} + 0.25$	$V_{TT} - 0.475$	$V_{TT} + 0.475$	6.7	-6.7
SSTL-18 Class II	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	$V_{CCIO} + 0.3$	$V_{REF} - 0.25$	$V_{REF} + 0.25$	0.28	$V_{CCIO} - 0.28$	13.4	-13.4
SSTL-15 Class I	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCIO} + 0.3$	$V_{REF} - 0.175$	$V_{REF} + 0.175$	$0.2 \times V_{CCIO}$	$0.8 \times V_{CCIO}$	8	-8
SSTL-15 Class II	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCIO} + 0.3$	$V_{REF} - 0.175$	$V_{REF} + 0.175$	$0.2 \times V_{CCIO}$	$0.8 \times V_{CCIO}$	16	-16
HSTL-18 Class I	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCIO} + 0.3$	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	8	-8
HSTL-18 Class II	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCIO} + 0.3$	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	16	-16
HSTL-15 Class I	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCIO} + 0.3$	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	8	-8
HSTL-15 Class II	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCIO} + 0.3$	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	16	-16
HSTL-12 Class I	-0.15	$V_{REF} - 0.08$	$V_{REF} + 0.08$	$V_{CCIO} + 0.15$	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.25 \times V_{CCIO}$	$0.75 \times V_{CCIO}$	8	-8
HSTL-12 Class II	-0.15	$V_{REF} - 0.08$	$V_{REF} + 0.08$	$V_{CCIO} + 0.15$	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.25 \times V_{CCIO}$	$0.75 \times V_{CCIO}$	14	-14

Table 1-27 lists the single-ended SSTL and HSTL I/O standard signal specifications for Arria II GZ devices.

Table 1-27. Single-Ended SSTL and HSTL I/O Standards Signal Specifications for Arria II GZ Devices (Part 1 of 2)

I/O Standard	$V_{IL(DC)} (V)$		$V_{IH(DC)} (V)$		$V_{IL(AC)} (V)$	$V_{IH(AC)} (V)$	$V_{OL} (V)$	$V_{OH} (V)$	$I_{OL} (mA)$	$I_{OH} (mA)$
	Min	Max	Min	Max	Max	Min	Max	Min		
SSTL-2 Class I	-0.3	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$V_{CCIO} + 0.3$	$V_{REF} - 0.31$	$V_{REF} + 0.31$	$V_{TT} - 0.57$	$V_{TT} + 0.57$	8.1	-8.1
SSTL-2 Class II	-0.3	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$V_{CCIO} + 0.3$	$V_{REF} - 0.31$	$V_{REF} + 0.31$	$V_{TT} - 0.76$	$V_{TT} + 0.76$	16.2	-16.2
SSTL-18 Class I	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	$V_{CCIO} + 0.3$	$V_{REF} - 0.25$	$V_{REF} + 0.25$	$V_{TT} - 0.475$	$V_{TT} + 0.475$	6.7	-6.7
SSTL-18 Class II	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	$V_{CCIO} + 0.3$	$V_{REF} - 0.25$	$V_{REF} + 0.25$	0.28	$V_{CCIO} - 0.28$	13.4	-13.4
SSTL-15 Class I	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.175$	$V_{REF} + 0.175$	$0.2 \times V_{CCIO}$	$0.8 \times V_{CCIO}$	8	-8

Table 1–34. Transceiver Specifications for Arria II GX Devices (Note 1) (Part 5 of 7)

Symbol/ Description	Condition	I3			C4			C5 and I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
LTD lock time (11)	—	0	100	4000	0	100	4000	0	100	4000	0	100	4000	ns
Data lock time from rx_ freqlocked (12)	—	—	—	4000	—	—	4000	—	—	4000	—	—	4000	ns
Programmable DC gain	DC Gain Setting = 0	—	0	—	—	0	—	—	0	—	—	0	—	dB
	DC Gain Setting = 1	—	3	—	—	3	—	—	3	—	—	3	—	dB
	DC Gain Setting = 2	—	6	—	—	6	—	—	6	—	—	6	—	dB
Transmitter														
Supported I/O Standards	1.5-V PCML													
Data rate	—	600	—	6375	600	—	3750	600	—	3750	600	—	3125	Mbps
V _{OCM}	0.65 V setting	—	650	—	—	650	—	—	650	—	—	650	—	mV
Differential on-chip termination resistors	100-Ω setting	—	100	—	—	100	—	—	100	—	—	100	—	Ω
Return loss differential mode	PCIe	50 MHz to 1.25 GHz: –10dB												
	XAUI	312 MHz to 625 MHz: –10dB 625 MHz to 3.125 GHz: –10dB/decade slope												
Return loss common mode	PCIe	50 MHz to 1.25 GHz: –6dB												
Rise time (2)	—	50	—	200	50	—	200	50	—	200	50	—	200	ps
Fall time	—	50	—	200	50	—	200	50	—	200	50	—	200	ps

Table 1–35. Transceiver Specifications for Arria II GZ Devices (Part 4 of 5)

Symbol/ Description	Conditions	–C3 and –I3 (1)			–C4 and –I4			Unit
		Min	Typ	Max	Min	Typ	Max	
Transmitter								
Supported I/O Standards	1.5-V PCML							
Data rate (14)	—	600	—	6375	600	—	3750	Mbps
V _{OCM}	0.65 V setting	—	650	—	—	650	—	mV
Differential on-chip termination resistors	85–Ω setting	85 ± 15%			85 ± 15%			Ω
	100–Ω setting	100 ± 15%			100 ± 15%			Ω
	120–Ω setting	120 ± 15%			120 ± 15%			Ω
	150–Ω setting	150 ± 15%			150 ± 15%			Ω
Differential and common mode return loss	PCIe Gen1 and Gen2 (TX V _{OD} =4), XAUI (TX V _{OD} =6), HiGig+ (TX V _{OD} =6), CEI SR/LR (TX V _{OD} =8), SRIO SR (V _{OD} =6), SRIO LR (V _{OD} =8), CPRI LV (V _{OD} =6), CPRI HV (V _{OD} =2), OBSAI (V _{OD} =6), SATA (V _{OD} =4),	Compliant						—
Rise time (15)	—	50	—	200	50	—	200	ps
Fall time (15)	—	50	—	200	50	—	200	ps
Intra-differential pair skew	—	—	—	15	—	—	15	ps
Intra-transceiver block transmitter channel-to-channel skew	×4 PMA and PCS bonded mode Example: XAUI, PCIe ×4, Basic ×4	—	—	120	—	—	120	ps
Inter-transceiver block transmitter channel-to-channel skew	×8 PMA and PCS bonded mode Example: PCIe ×8, Basic ×8	—	—	500	—	—	500	ps
CMU0 PLL and CMU1 PLL								
Supported Data Range	—	600	—	6375	600	—	3750	Mbps
pll_powerdown minimum pulse width (tp _{pll_powerdown})	—	1			1			μs
CMU PLL lock time from pll_powerdown de-assertion	—	—	—	100	—	—	100	μs

Table 1–37 lists the typical V_{OD} for TX term that equals $100\ \Omega$ for Arria II GX and GZ devices.

Table 1–37. Typical V_{OD} Setting, TX Termination = $100\ \Omega$ for Arria II Devices

Quartus II Setting	V_{OD} Setting (mV)
1	400
2	600
3 (Arria II GZ)	700
4	800
5	900
6	1000
7	1200

Table 1–38 lists the typical transmitter pre-emphasis levels in dB for the first post tap under the following conditions: low-frequency data pattern (five 1s and five 0s) at 6.375 Gbps. The levels listed in Table 1–38 are a representation of possible pre-emphasis levels under these specified conditions only, the pre-emphasis levels may change with data pattern and data rate.

To predict the pre-emphasis level for your specific data rate and pattern, run simulations using the Arria II GX HSSI HSPICE models.

Table 1–38. Transmitter Pre-Emphasis Levels for Arria II GX Devices

Arria II GX (Quartus II Software) First Post Tap Setting	Arria II GX (Quartus II Software) VOD Setting						Unit
	1	2	4	5	6	7	
0 (off)	0	0	0	0	0	0	—
1	0.7	0	0	0	0	0	dB
2	2.7	1.2	0.3	0	0	0	dB
3	4.9	2.4	1.2	0.8	0.5	0.2	dB
4	7.5	3.8	2.1	1.6	1.2	0.6	dB
5	—	5.3	3.1	2.4	1.8	1.1	dB
6	—	7	4.3	3.3	2.7	1.7	dB

Table 1–39 lists typical transmitter pre-emphasis levels for Arria II GZ devices (in dB) for the first post tap under the following conditions (low-frequency data pattern [five 1s and five 0s] at 6.25 Gbps). The levels listed in Table 1–39 are a representation of possible pre-emphasis levels under the specified conditions only and that the pre-emphasis levels may change with data pattern and data rate.



To predict the pre-emphasis level for your specific data rate and pattern, run simulations using the [Arria II HSSI HSPICE](#) models.

Table 1–39. Transmitter Pre-Emphasis Levels for Arria II GZ Devices (Part 1 of 2)

Pre-Emphasis 1st Post-Tap Setting	V _{DD} Setting							
	0	1	2	3	4	5	6	7
0	0	0	0	0	0	0	0	0
1	N/A	0.7	0	0	0	0	0	0
2	N/A	1	0.3	0	0	0	0	0
3	N/A	1.5	0.6	0	0	0	0	0
4	N/A	2	0.7	0.3	0	0	0	0
5	N/A	2.7	1.2	0.5	0.3	0	0	0
6	N/A	3.1	1.3	0.8	0.5	0.2	0	0
7	N/A	3.7	1.8	1.1	0.7	0.4	0.2	0
8	N/A	4.2	2.1	1.3	0.9	0.6	0.3	0
9	N/A	4.9	2.4	1.6	1.2	0.8	0.5	0.2
10	N/A	5.4	2.8	1.9	1.4	1	0.7	0.3
11	N/A	6	3.2	2.2	1.7	1.2	0.9	0.4
12	N/A	6.8	3.5	2.6	1.9	1.4	1.1	0.6
13	N/A	7.5	3.8	2.8	2.1	1.6	1.2	0.6
14	N/A	8.1	4.2	3.1	2.3	1.7	1.3	0.7
15	N/A	8.8	4.5	3.4	2.6	1.9	1.5	0.8
16	N/A	N/A	4.9	3.7	2.9	2.2	1.7	0.9
17	N/A	N/A	5.3	4	3.1	2.4	1.8	1.1
18	N/A	N/A	5.7	4.4	3.4	2.6	2	1.2
19	N/A	N/A	6.1	4.7	3.6	2.8	2.2	1.4
20	N/A	N/A	6.6	5.1	4	3.1	2.4	1.5
21	N/A	N/A	7	5.4	4.3	3.3	2.7	1.7
22	N/A	N/A	8	6.1	4.8	3.8	3	2
23	N/A	N/A	9	6.8	5.4	4.3	3.4	2.3
24	N/A	N/A	10	7.6	6	4.8	3.9	2.6
25	N/A	N/A	11.4	8.4	6.8	5.4	4.4	3
26	N/A	N/A	12.6	9.4	7.4	5.9	4.9	3.3
27	N/A	N/A	N/A	10.3	8.1	6.4	5.3	3.6
28	N/A	N/A	N/A	11.3	8.8	7.1	5.8	4

Table 1–40. Transceiver Block Jitter Specifications for Arria II GX Devices (Note 1) (Part 2 of 10)

Symbol/ Description	Conditions	I3			C4			C5, I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Jitter tolerance at 2488.32 Mbps	Jitter frequency = 0.06 KHz Pattern = PRBS15	> 15			> 15			> 15			> 15			UI
	Jitter frequency = 100 KHz Pattern = PRBS15	> 1.5			> 1.5			> 1.5			> 1.5			UI
	Jitter frequency = 1 MHz Pattern = PRBS15	> 0.15			> 0.15			> 0.15			> 0.15			UI
	Jitter frequency = 10 MHz Pattern = PRBS15	> 0.15			> 0.15			> 0.15			> 0.15			UI
XAUI Transmit Jitter Generation (3)														
Total jitter at 3.125 Gbps	Pattern = CJPAT	—	—	0.3	—	—	0.3	—	—	0.3	—	—	0.3	UI
Deterministic jitter at 3.125 Gbps	Pattern = CJPAT	—	—	0.17	—	—	0.17	—	—	0.17	—	—	0.17	UI
XAUI Receiver Jitter Tolerance (3)														
Total jitter	—	> 0.65			> 0.65			> 0.65			> 0.65			UI
Deterministic jitter	—	> 0.37			> 0.37			> 0.37			> 0.37			UI
Peak-to-peak jitter	Jitter frequency = 22.1 KHz	> 8.5			> 8.5			> 8.5			> 8.5			UI
Peak-to-peak jitter	Jitter frequency = 1.875 MHz	> 0.1			> 0.1			> 0.1			> 0.1			UI
Peak-to-peak jitter	Jitter frequency = 20 MHz	> 0.1			> 0.1			> 0.1			> 0.1			UI
PCIe Transmit Jitter Generation (4)														
Total jitter at 2.5 Gbps (Gen1)	Compliance pattern	—	—	0.25	—	—	0.25	—	—	0.25	—	—	0.25	UI

Table 1–40. Transceiver Block Jitter Specifications for Arria II GX Devices (Note 1) (Part 5 of 10)

Symbol/ Description	Conditions	I3			C4			C5, I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
SDI Transmitter Jitter Generation (8)														
Alignment jitter (peak-to-peak)	Data rate = 1.485 Gbps (HD) pattern = Color Bar Low- frequency Roll-off = 100 KHz	0.2	—	—	0.2	—	—	0.2	—	—	0.2	—	—	UI
	Data rate = 2.97 Gbps (3G) pattern = Color bar Low- frequency Roll-off = 100 KHz	0.3	—	—	0.3	—	—	0.3	—	—	0.3	—	—	UI
SDI Receiver Jitter Tolerance (8)														
Sinusoidal jitter tolerance (peak-to-peak)	Jitter frequency = 15 KHz Data rate = 2.97 Gbps (3G) Pattern = single line scramble color bar	> 2			> 2			> 2			> 2			UI
	Jitter frequency = 100 KHz Data rate = 2.97 Gbps (3G) Pattern = single line scramble color bar	> 0.3			> 0.3			> 0.3			> 0.3			UI
	Jitter frequency = 148.5 MHz Data rate = 2.97 Gbps (3G) Pattern = single line scramble color bar	> 0.3			> 0.3			> 0.3			> 0.3			UI

Table 1–41. Transceiver Block Jitter Specifications for Arria II GZ Devices (Note 1), (2) (Part 3 of 7)

Symbol/ Description	Conditions	–C3 and –I3			–C4 and –I4			Unit
		Min	Typ	Max	Min	Typ	Max	
Peak-to-peak jitter	Jitter frequency = 22.1 KHz	> 8.5			> 8.5			UI
Peak-to-peak jitter	Jitter frequency = 1.875 MHz	> 0.1			> 0.1			UI
Peak-to-peak jitter	Jitter frequency = 20 MHz	> 0.1			> 0.1			UI
PCIe Transmit Jitter Generation (8)								
Total jitter at 2.5 Gbps (Gen1)— x1, x4, and x8	Compliance pattern	—	—	0.25	—	—	0.25	UI
Total jitter at 5 Gbps (Gen2)— x1, x4, and x8	Compliance pattern	—	—	0.25	—	—	—	UI
PCIe Receiver Jitter Tolerance (8)								
Total jitter at 2.5 Gbps (Gen1)	Compliance pattern	> 0.6			> 0.6			UI
Total jitter at 5 Gbps (Gen2)	Compliance pattern	Not supported			Not supported			UI
PCIe (Gen 1) Electrical Idle Detect Threshold								
V _{RX-IDLE-DETDIFFp-p} (9)	Compliance pattern	65	—	175	65	—	175	UI
SRIO Transmit Jitter Generation (10)								
Deterministic jitter (peak-to-peak)	Data rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	—	—	0.17	—	—	0.17	UI
Total jitter (peak-to-peak)	Data rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	—	—	0.35	—	—	0.35	UI
SRIO Receiver Jitter Tolerance (10)								
Deterministic jitter tolerance (peak-to-peak)	Data rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	> 0.37			> 0.37			UI
Combined deterministic and random jitter tolerance (peak-to- peak)	Data rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	> 0.55			> 0.55			UI
Sinusoidal jitter tolerance (peak- to-peak)	Jitter frequency = 22.1 KHz Data rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	> 8.5			> 8.5			UI
	Jitter frequency = 1.875 MHz Data rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	> 0.1			> 0.1			UI
	Jitter frequency = 20 MHz Data rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	> 0.1			> 0.1			UI
GIGE Transmit Jitter Generation (11)								
Deterministic jitter (peak-to-peak)	Pattern = CRPAT	—	—	0.14	—	—	0.14	UI
Total jitter (peak-to-peak)	Pattern = CRPAT	—	—	0.279	—	—	0.279	UI

Table 1–41. Transceiver Block Jitter Specifications for Arria II GZ Devices (Note 1), (2) (Part 5 of 7)

Symbol/ Description	Conditions	–C3 and –I3			–C4 and –I4			Unit
		Min	Typ	Max	Min	Typ	Max	
Sinusoidal jitter tolerance (peak-to-peak)	Jitter Frequency = 38.2 KHz Data rate = 6.375 Gbps Pattern = PRBS31 BER = 10 ⁻¹²	> 0.5			—	—	—	UI
	Jitter Frequency = 3.82 MHz Data rate = 6.375 Gbps Pattern = PRBS31 BER = 10 ⁻¹²	> 0.05			—	—	—	UI
	Jitter Frequency = 20 MHz Data rate = 6.375 Gbps Pattern = PRBS31 BER = 10 ⁻¹²	> 0.05			—	—	—	UI
SDI Transmitter Jitter Generation (12)								
Alignment jitter (peak-to-peak)	Data rate = 1.485 Gbps (HD) Pattern = color bar Low-frequency roll-off = 100 KHz	0.2	—	—	0.2	—	—	UI
	Data rate = 2.97 Gbps (3G) Pattern = color bar Low-frequency roll-off = 100 KHz	0.3	—	—	0.3	—	—	UI
SDI Receiver Jitter Tolerance (12)								
Sinusoidal jitter tolerance (peak-to-peak)	Jitter frequency = 15 KHz Data rate = 2.97 Gbps (3G) Pattern = single line scramble color bar	> 2			> 2			UI
	Jitter frequency = 100 KHz Data rate = 2.97 Gbps (3G) Pattern = single line scramble color bar	> 0.3			> 0.3			UI
	Jitter frequency = 148.5 MHz Data rate = 2.97 Gbps (3G) Pattern = single line scramble color bar	> 0.3			> 0.3			UI
Sinusoidal jitter tolerance (peak-to-peak)	Jitter frequency = 20 KHz Data rate = 1.485 Gbps (HD) pattern = 75% color bar	> 1			> 1			UI
	Jitter frequency = 100 KHz Data rate = 1.485 Gbps (HD) Pattern = 75% color bar	> 0.2			> 0.2			UI
	Jitter frequency = 148.5 MHz Data rate = 1.485 Gbps (HD) Pattern = 75% color bar	> 0.2			> 0.2			UI
SAS Transmit Jitter Generation (13)								
Total jitter at 1.5 Gbps (G1)	Pattern = CJPAT	—	—	0.55	—	—	0.55	UI
Deterministic jitter at 1.5 Gbps (G1)	Pattern = CJPAT	—	—	0.35	—	—	0.35	UI
Total jitter at 3.0 Gbps (G2)	Pattern = CJPAT	—	—	0.55	—	—	0.55	UI

Table 1–41. Transceiver Block Jitter Specifications for Arria II GZ Devices (Note 1), (2) (Part 7 of 7)

Symbol/ Description	Conditions	–C3 and –I3			–C4 and –I4			Unit
		Min	Typ	Max	Min	Typ	Max	
OBSAI Receiver Jitter Tolerance (15)								
Deterministic jitter tolerance at 768 Mbps, 1536 Mbps, and 3072 Mbps	Pattern = CJPAT	> 0.37			> 0.37			UI
Combined deterministic and random jitter tolerance at 768 Mbps, 1536 Mbps, and 3072 Mbps	Pattern = CJPAT	> 0.55			> 0.55			UI
Sinusoidal jitter tolerance at 768 Mbps	Jitter frequency = 5.4 KHz Pattern = CJPAT	> 8.5			> 8.5			UI
	Jitter frequency = 460 MHz to 20 MHz Pattern = CJPAT	> 0.1			> 0.1			UI
Sinusoidal jitter tolerance at 1536 Mbps	Jitter frequency = 10.9 KHz Pattern = CJPAT	> 8.5			> 8.5			UI
	Jitter frequency = 921.6 MHz to 20 MHz Pattern = CJPAT	> 0.1			> 0.1			UI
Sinusoidal jitter tolerance at 3072 Mbps	Jitter frequency = 21.8 KHz Pattern = CJPAT	> 8.5			> 8.5			UI
	Jitter frequency = 1843.2 MHz to 20 MHz Pattern = CJPAT	> 0.1			> 0.1			UI

Notes to Table 1–41:

- (1) Dedicated `refclk` pins were used to drive the input reference clocks.
- (2) The jitter numbers are valid for the stated conditions only.
- (3) The jitter numbers for SONET/SDH are compliant to the GR-253-CORE Issue 3 Specification.
- (4) The jitter numbers for Fibre Channel are compliant to the FC-P1-4 Specification revision 6.10.
- (5) The Fibre Channel transmitter jitter generation numbers are compliant to the specification at the δ_T inter operability point.
- (6) The Fibre Channel receiver jitter tolerance numbers are compliant to the specification at the δ_R interpretability point.
- (7) The jitter numbers for XAUI are compliant to the IEEE802.3ae-2002 Specification.
- (8) The jitter numbers for PCIe are compliant to the PCIe Base Specification 2.0.
- (9) Arria II GZ PCIe receivers are compliant to this specification provided the $V_{TX-CM-DC-ACTIVEIDLE-DELTA}$ of the upstream transmitter is less than 50 mV.
- (10) The jitter numbers for SRIO are compliant to the RapidIO Specification 1.3.
- (11) The jitter numbers for GIGE are compliant to the IEEE802.3-2002 Specification.
- (12) The HD-SDI and 3G-SDI jitter numbers are compliant to the SMPTE292M and SMPTE424M Specifications.
- (13) The jitter numbers for Serial Attached SCSI (SAS) are compliant to the SAS-2.1 Specification.
- (14) The jitter numbers for CPRI are compliant to the CPRI Specification V3.0.
- (15) The jitter numbers for OBSAI are compliant to the OBSAI RP3 Specification V4.1.

Table 1-53. High-Speed I/O Specifications for Arria II GX Devices (Part 3 of 4)

Symbol	Conditions	I3		C4		C5,I5		C6		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
t_{TX_JITTER} (4)	True LVDS with dedicated SERDES (data rate 600–1,250 Mbps)	—	175	—	175	—	225	—	300	ps
	True LVDS with dedicated SERDES (data rate < 600 Mbps)	—	0.105	—	0.105	—	0.135	—	0.18	UI
	True LVDS and emulated LVDS_E_3R with logic elements as SERDES (data rate 600 – 945 Mbps)	—	260	—	260	—	300	—	350	ps
	True LVDS and emulated LVDS_E_3R with logic elements as SERDES (data rate < 600 Mbps)	—	0.16	—	0.16	—	0.18	—	0.21	UI
t_{TX_DCD}	True LVDS and emulated LVDS_E_3R	45	55	45	55	45	55	45	55	%
t_{RISE} and t_{FALL}	True LVDS and emulated LVDS_E_3R	—	200	—	200	—	225	—	250	ps
TCCS	True LVDS (5)	—	150	—	150	—	175	—	200	ps
	Emulated LVDS_E_3R	—	200	—	200	—	250	—	300	ps
Receiver (6)										
True differential I/O standards - f_{HSDRPA} (data rate)	SERDES factor J = 3 to 10	150	1250	150	1250	150	1050	150	840	Mbps

Table 1–53. High-Speed I/O Specifications for Arria II GX Devices (Part 4 of 4)

Symbol	Conditions	I3		C4		C5,I5		C6		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
f_{HSDR} (data rate)	SERDES factor J = 3 to 10	(3)	945 (7)	(3)	945 (7)	(3)	740 (7)	(3)	640 (7)	Mbps
	SERDES factor J = 2 (using DDR registers)	(3)	(7)	(3)	(7)	(3)	(7)	(3)	(7)	Mbps
	SERDES factor J = 1 (using SDR registers)	(3)	(7)	(3)	(7)	(3)	(7)	(3)	(7)	Mbps
Soft-CDR PPM tolerance	Soft-CDR mode	—	300	—	300	—	300	—	300	±PPM
DPA run length	DPA mode	—	10,000	—	10,000	—	10,000	—	10,000	UI
Sampling window (SW)	Non-DPA mode (5)	—	300	—	300	—	350	—	400	ps

Notes to Table 1–53:

- (1) $f_{\text{HCLK_IN}} = f_{\text{HSDR}} / W$. Use W to determine the supported selection of input reference clock frequencies for the desired data rate.
- (2) Applicable for interfacing with DPA receivers only. For interfacing with non-DPA receivers, you must calculate the leftover timing margin in the receiver by performing link timing closure analysis. For Arria II GX transmitter to Arria II GX non-DPA receiver, the maximum supported data rate is 945 Mbps. For data rates above 840 Mbps, perform PCB trace compensation by adjusting the PCB trace length for LVDS channels to improve channel-to-channel skews.
- (3) The minimum and maximum specification depends on the clock source (for example, PLL and clock pin) and the clock routing resource you use (global, regional, or local). The I/O differential buffer and input register do not have a minimum toggle rate.
- (4) The specification is only applicable under the influence of core noise.
- (5) Applicable for true LVDS using dedicated SERDES only.
- (6) Dedicated SERDES and DPA features are only available on the right banks.
- (7) You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and the receiver sampling margin to determine the leftover timing margin.

Table 1–54 lists the high-speed I/O timing for Arria II GZ devices.

Table 1–54. High-Speed I/O Specifications for Arria II GZ Devices (Note 1), (2), (10) (Part 1 of 3)

Symbol	Conditions	C3, I3			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	
Clock								
f _{HCLK_in} (input clock frequency) true differential I/O standards	Clock boost factor W = 1 to 40 (3)	5	—	717	5	—	717	MHz
f _{HCLK_in} (input clock frequency) single ended I/O standards (9)	Clock boost factor W = 1 to 40 (3)	5	—	717	5	—	717	MHz
f _{HCLK_in} (input clock frequency) single ended I/O standards (10)	Clock boost factor W = 1 to 40 (3)	5	—	420	5	—	420	MHz

Table 1–54. High-Speed I/O Specifications for Arria II GZ Devices (Note 1), (2), (10) (Part 3 of 3)

Symbol	Conditions	C3, I3			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	
$t_{RISE} \& t_{FALL}$	True differential I/O standards	—	—	200	—	—	200	ps
	Emulated differential I/O standards with three external output resistor networks	—	—	250	—	—	300	ps
	Emulated differential I/O standards with one external output resistor	—	—	500	—	—	500	ps
TCCS	True LVDS	—	—	100	—	—	100	ps
	Emulated LVDS_E_3R	—	—	250	—	—	250	ps
Receiver								
True differential I/O standards - f_{HSDRDA} (data rate)	SERDES factor J = 3 to 10	150	—	1250	150	—	1250	Mbps
f_{HSDR} (data rate)	SERDES factor J = 3 to 10	(4)	—	(6)	(4)	—	(6)	Mbps
	SERDES factor J = 2, uses DDR registers	(4)	—	(5)	(4)	—	(5)	Mbps
	SERDES factor J = 1, uses an SDR register	(4)	—	(5)	(4)	—	(5)	Mbps
DPA run length	DPA mode	—	—	10000	—	—	10000	UI
Soft-CDR PPM tolerance	Soft-CDR mode	—	—	300	—	—	300	± PPM
Sampling Window (SW)	Non-DPA mode	—	—	300	—	—	300	ps

Notes to Table 1–54:

- (1) When J = 3 to 10, use the SERDES block.
- (2) When J = 1 or 2, bypass the SERDES block.
- (3) Clock Boost Factor (W) is the ratio between input data rate to the input clock rate.
- (4) The minimum specification depends on the clock source (for example, the PLL and clock pin) and the clock routing resource (global, regional, or local) that you use. The I/O differential buffer and input register do not have a minimum toggle rate.
- (5) You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and receiver sampling margin to determine leftover timing margin.
- (6) You can estimate the achievable maximum data rate for non-DPA mode by performing link timing closure analysis. You must consider the board skew margin, transmitter delay margin, and the receiver sampling margin to determine the maximum data rate supported.
- (7) This is achieved by using the LVDS and DPA clock network.
- (8) If the receiver with DPA enabled and transmitter are using shared PLLs, the minimum data rate is 150 Mbps.
- (9) This only applies to DPA and soft-CDR modes.
- (10) This only applies to LVDS source synchronous mode.

Table 1–55 lists DPA lock time specifications for Arria II GX and GZ devices.

I/O Timing

Altera offers two ways to determine I/O timing:

- Using the Microsoft Excel-based I/O Timing.
- Using the Quartus II Timing Analyzer.

The Microsoft Excel-based I/O Timing provides pin timing performance for each device density and speed grade. The data is typically used prior to designing the FPGA to get an estimate of the timing budget as part of the link timing analysis. The Quartus II timing analyzer provides a more accurate and precise I/O timing data based on the specifics of the design after place-and-route is complete.



The Microsoft Excel-based I/O Timing spreadsheet is downloadable from the [Literature: Arria II Devices](#) web page.

Table 1–68. Glossary (Part 4 of 4)

Letter	Subject	Definitions
U, V	$V_{CM(DC)}$	DC common mode input voltage.
	V_{ICM}	Input common mode voltage: The common mode of the differential signal at the receiver.
	V_{ID}	Input differential voltage swing: The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.
	$V_{DIF(AC)}$	AC differential input voltage: Minimum AC input differential voltage required for switching.
	$V_{DIF(DC)}$	DC differential input voltage: Minimum DC input differential voltage required for switching.
	V_{IH}	Voltage input high: The minimum positive voltage applied to the input which is accepted by the device as a logic high.
	$V_{IH(AC)}$	High-level AC input voltage.
	$V_{IH(DC)}$	High-level DC input voltage.
	V_{IL}	Voltage input low: The maximum positive voltage applied to the input which is accepted by the device as a logic low.
	$V_{IL(AC)}$	Low-level AC input voltage.
	$V_{IL(DC)}$	Low-level DC input voltage.
	V_{OCM}	Output common mode voltage: The common mode of the differential signal at the transmitter.
	V_{OD}	Output differential voltage swing: The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter.
W, X, Y, Z	W	High-speed I/O block: The clock boost factor.

Document Revision History

Table 1–69 lists the revision history for this chapter.

Table 1–69. Document Revision History (Part 1 of 2)

Date	Version	Changes
December 2013	4.4	Updated Table 1–34 and Table 1–35.
July 2012	4.3	- Updated the $V_{CCH_GXBL/R}$ operating conditions in Table 1–6. - Finalized Arria II GZ information in Table 1–20. - Added BLVDS specification in Table 1–32 and Table 1–33. - Updated input and output waveforms in Table 1–68.
December 2011	4.2	- Updated Table 1–32, Table 1–33, Table 1–34, Table 1–35, Table 1–40, Table 1–41, Table 1–54, and Table 1–67. - Minor text edits.
June 2011	4.1	- Added Table 1–60. - Updated Table 1–32, Table 1–33, Table 1–38, Table 1–41, and Table 1–61. - Updated the “Switching Characteristics” section introduction. - Minor text edits.